

# **Product Change Notification - LIAL-08UVRX401**

# Date:

30 Apr 2018 **Product Category:** Ethernet Controllers; Others **Affected CPNs:** 

# Notification subject:

CCB 3285 Initial Notice: Qualification of ASE as a new assembly site for selected products of the 0.18um wafer technology at DBHU available in 48L LQFP (7x7x1.4 mm) package.

# Notification text:

PCN Status: Initial notification.

## PCN Type:

Manufacturing Change

## **Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

**NOTE:** For your convenience Microchip includes identical files in two formats (.pdf and .xls)

### **Description of Change:**

Qualification of ASE as a new assembly site for selected products of the 0.18um wafer technology at DBHU available in 48L LQFP (7x7x1.4 mm) package.

#### Pre Change:

Assembled at TICP assembly site using CEL-9200 mold compound material.

## Post Change:

Assembled at ASE assembly site using EME-G631H mold compound material.

#### Pre and Post Change Summary:

	Pre Change	Post Change				
Assembly Site	Taiwan IC Packing Corp. (TICP)	ASE Inc. (ASE)				
Wire material	Au	Au				
Die attach material	EN4900	EN4900				
Molding compound material	CEL-9200	EME-G631H				
Lead frame material	C7025	C7025				

#### Impacts to Data Sheet:

None

#### Change Impact:

None

#### **Reason for Change:**

To improve manufacturability by qualifying ASE as new assembly site

Change Implementation Status:

In Progress

# Estimated Qualification Completion Date:

August 2018

Note: Please be advised the qualification completion times may be extended because of



unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

#### Time Table Summary:

		March 2018					August 2018				
Workweek	09	10	11	12	13	>	31	32	33	34	35
Initial PCN Issue Date					Х						
Qual Report Availability											Х
Final PCN Issue Date											Х

#### Method to Identify Change:

Traceability code

#### **Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan

#### **Revision History:**

March 28, 2018: Issued initial notification.

**April 20, 2018:** Re-issued initial notification to update the Qual plan and to correct the date on initial notification revision history.

**April 30, 2018:** Re-issued initial notification to correct the attachment for the affected CPN list. The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

# Attachment(s):

PCN\_LIAL-08UVRX401\_QUAL PLAN.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

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To opt out of future offer or information emails (other than product change notification emails), click here to go to microchip DIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

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Affected Catalog Part Numbers (CPN)

KSZ8851-16MLLI KSZ8851-16MLLI-TR KSZ8851-16MLLJ KSZ8851-16MLLJ KSZ8851-16MLLU KSZ8851-16MLLU KSZ8851-16MLLU-TR SPNY801062 SPNZ801062